**PATENT** 

Docket No.:JCLA8288-D

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

**Applicant** 

: CHI-HSING HSU et al.

Filed

: Herewith

For

: SEMICONDUCTOR PACKAGING SUBSTRATE AND

METHOD OF PRODUCING THE SAME

## **PRELIMINARY AMENDMENT**

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Prior to the examination on merits, please amend the above-identified application as shown in the attached sheets. No new matter has added through the amendment. Entry of the amendment is requested.

Respectfully submitted,

Dated: 1-28-2004

Jiawei Huang

Registration No. 43,330

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